

Reada PCB Technology Co.,Ltd

| ITEM | Manufacturing Capability |
|---|---|
| Layers | 2L-32L (HDI:4+N+4) For Small lots, 2-18Layers(HDI:1+N+1 2+N+2) For large volume |
| Base Materials : | CEM3, FR4, Metal Core , Polymide, ISOLA, Teflon, Rogers |
| Surface Treatment | HAL, Lead Free HAL, Gold Plating, Immersion Gold, OSP, HAL+G/F, Immersion Silver, Immersion Tin |
| Max Panel size | Min 10*10mm ; Max : 1200*500mm |
| Board Thickness | 0.20 ~ 6.50mm |
| Conductor width/spacing | Min: 2.0/2.0mil |
| Registration | 3.0mil |
| External Cu Thickness | HOZ-6OZ |
| Internal Cu Thickness | HOZ-6OZ |
| Min. Drilling Diameter | Mechanical Drilling: ≥0.2mm , Laser Drilling:< 0.1mm |
| Hole Wall Wopper Thickness | ≥20um |
| Uniformity | ≥90% |
| Aspect Ratio | 10:1 |
| Solder Mask Bridge | 3.0mil |
| Plug Hole Dia. | 0.30 ~ 0.60mm |
| Slot Size | Min : 0.80mm |
| V-CUT Angle | 15° 30° 45° |
| Beveling Angle | 20° 30° 45° 60° |
| Tolerance | |
| Trace width/space | ±15%mil |
| BGA & SMT PAD Size | ±10%mil |
| PTH Diameter | ±2mil |
| NPTH Diameter | ±1mil |
| PTH Slot Length | ±3mil |
| NPTH Slot Length | ±2mil |
| Hole to Hole Location | ±2mil |
| Hole to edge dimension | ±4mil |
| Edge to edge dimension | ±4mil |
| Layer to layer offset | ±3mil |
| Impedence value | ±8%ohm |
| V-CUT Tolerance | ±0.10mm |
| Outline Tolerance | ±0.13mm |
| Warp & Twist | ≤0.40% |
| Surface Finish | |
| Immersion Ni/Au | YES |
| Ni thickness | 2.50-6.00um |
| Au thickness | 0.025-0.100um |
| Flash Gold | YES |
| Ni thickness | 2.50-6.00um |
| Au thickness | 0.025-0.800um |
| OSP (F2 Chemical Liquid) | YES |
| OSP Thickness | 0.20-0.50um |
| Immersion Tin | YES |
| Tin Thickness | 0.80-1.20um |
| Immersion Ag | YES |
| HASL & PB Free HASL | YES |
| Solder thickness | 1.00-25.00um |
| Selective ENIG+OSP | YES |
| Others (Carbon ink & Peelable soldemas) | YES |